



Dow Electronic Materials Introduces New Metallization and Imaging Products for Printed Circuit Boards

Unique Technology Helps Create Smaller, More Sustainable, Less Expensive Consumer Electronics

Tayuan, Taiwan, October 27, 2009 – [Dow Electronic Materials](#) introduced its new line of metallization and imaging products for printed circuit boards (PCB) at the recent [TPCA show](#) and [IMPACT Conference](#). These advanced materials provide high-performance, cost effective solutions with improved environmental profiles for the PCB industry, and address the demand for smaller, more sustainable, less expensive and better performing consumer electronics.

- **PCB Electrolytic Plating** – [MICROFILL™ EVF Via Fill](#) provides greatly enhanced via filling at exceptionally low surface thicknesses and is capable of simultaneous through-hole plating. It is suitable for both HDI and IC (Integrated Circuit) Substrate applications. The company received an Outstanding Paper Award at recent IMPACT Conference for its excellent achievement in this area. [COPPER GLEAM™ HV-101 and HVS-202 Acid Copper](#) provide high plating efficiency which increases productivity and lowers plating cost for vertical continuous plating applications. [COPPER GLEAM™ MV-100 Acid Copper](#) exhibits exceptionally good metal distribution and better performance for vertical in-line equipment with dramatic improvement in cycle time.
- **PCB Making Holes Conductive** – [CIRCUPOSIT™ 3350-1 Electroless Copper](#) offers excellent plating coverage and reliability, stable operation, and reduced chemical consumption and waste generation for MLB (Multi-Layer Board) and HDI applications. [CIRCUPOSIT™ 7800 Desmear for SAP](#) (Semi-additive Process) delivers uniform and stable adhesion promotion treatment and reliable via bottom cleaning. It provides excellent plating coverage, high peeling strength and reliability. A new **Advanced Sweller** product provides cost-effective, wide operational window desmearing solutions for both normal and high performance laminates with reduced toxicity solvent and low concentration chemistry. [CIRCUPOSIT™ 3323A Conditioner](#) is a biodegradable conditioner for PTH (Plating Through Hole) processes. Its excellent coverage and lower surface tension provide exceptional performance and reliability.
- **PCB Final Finish** – [PALLAMERSE™ SMT 2000 Electroless Palladium](#) is designed for use in ENEPIG (Electroless Nickel Electroless Palladium Immersion Gold) processes for both SMT (Surface Mount Technology) soldering and gold wire bonding assembly applications. A new **Low Gold Immersion Gold** offers a highly economical immersion gold option for ENIG (Electroless Nickel Immersion Gold) processes. It sustains uniform gold thickness distribution and reliable solderability with reduced gold consumption.
- **PCB Imaging** – [EAGLE™ 2100 Photoresist](#) is the latest 3-D negative electrodeposited photoresist which is designed for a variety of substrate sizes and geometries. It provides uniform and defect-free coatings and excellent resolution.
- **New products under development** include Advanced SAP Metallization solutions and [CIRCUPOSIT™ 71 Full-Build Electroless Copper](#). These products are planned to be commercially available next year.



"The strength of Dow Electronic Materials comes from our ability to closely partner with industry-leading customers to develop next generation materials," said Bob Ferguson, global general manager for Dow Electronic Materials. "As a leader in metallization technologies, we are excited to present these high-performance, low-cost, and more sustainable solutions to the PCB industry. With our cutting-edge technology, outstanding customer service, strong technical support and global footprint, we are committed to deliver sustainable technologies for the evolving electronic world," he said.

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About Dow

Dow is a diversified chemical company that combines the power of science and technology with the "Human Element" to constantly improve what is essential to human progress. The Company delivers a broad range of products and services to customers in approximately 160 countries, connecting chemistry and innovation with the principles of sustainability to help provide everything from fresh water, food and pharmaceuticals to paints, packaging and personal care products. In 2008, Dow had annual sales of \$57.5 billion and employed approximately 46,000 people worldwide. The Company has 150 manufacturing sites in 35 countries and produces approximately 3,300 products. On April 1, 2009, Dow acquired Rohm and Haas Company, a global specialty materials company with sales of \$10 billion in 2008, 98 manufacturing sites in 30 countries and approximately 15,000 employees worldwide. References to "Dow" or the "Company" mean The Dow Chemical Company and its consolidated subsidiaries unless otherwise expressly noted. More information about Dow can be found at www.dow.com.

About Dow Electronic Materials

Dow Electronic Materials, a global supplier of materials and technologies to the electronics industry, brings innovative leadership to the semiconductor, [interconnect](#), [finishing](#), [photovoltaic](#), display, LED and optics markets. From advanced technology centers worldwide, teams of talented Dow research scientists and application experts work closely with customers, providing solutions, products and technical service necessary for next-generation electronics. These partnerships energize Dow's power to invent. Its key end-use applications include a broad range of consumer electronics from personal computers, to television monitors, cellular phones, global positioning systems, automobile safety systems, and avionics.

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